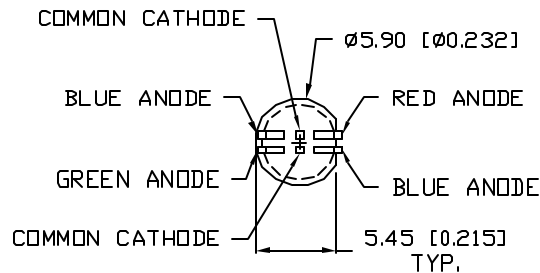
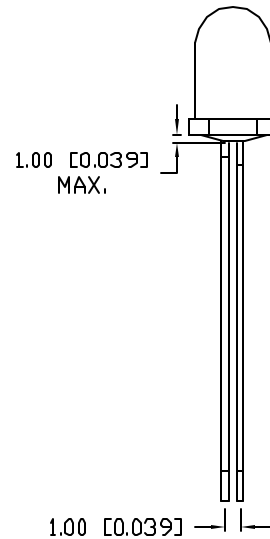
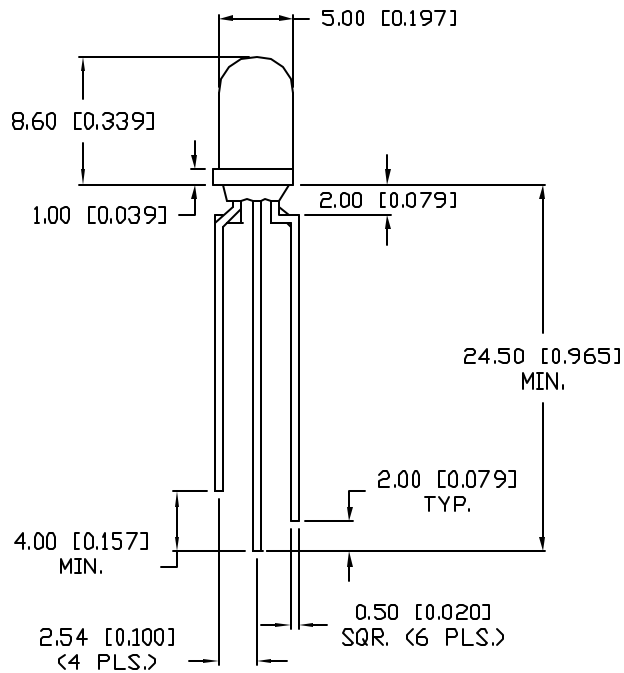
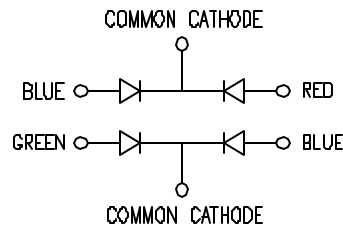


UNCONTROLLED DOCUMENT

PART NUMBER		REV.
SSL-LX5099SIUBSUGB		A
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #11148	11.08.06



BOTTOM VIEW POLARITY



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		636 (RED)		nm	
		574 (GREEN)		nm	
		470 (BLUE)		nm	
FORWARD VOLTAGE (R)		1.9	2.5	V_f	
(G)		2.1	2.5	V_f	
(B)		3.65	4.2	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_r=100\mu\text{A}$
AXIAL INTENSITY (R/G/B)		600/450/150		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		30		$2x$ theta	
EMITTED COLOR:	RED/GREEN/BLUE (MULTI-COLOR)				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*	(R/G/B)	185/205/160	mA
STEADY CURRENT		30	mA
POWER DISSIPATION	(R/G/B)	170/105/102	mW
DERATE FROM 25°C		-1.2	$\text{mW}/^\circ\text{C}$
OPERATING, STORAGE TEMP.		-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.		+260	$^\circ\text{C}$
2.0mm FROM BODY			3 SEC. MAX

* $t < 10\mu\text{s}$



*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN.=^{+0.00}_{-0.00} DECIMAL PRECISION MAX.=^{+0.00}_{-0.00} DECIMAL PRECISION

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REV.	PART NUMBER
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T-5mm (T-1 3/4) LED, 6 LEADED, MULTI-COLORED, 636nm AlInGaP RED/574nm AlInGaP GREEN BICOLOR, 470nm ULTRA SUPER BLUE, WATER CLEAR LENS.

RELIABILITY NOTE
 OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE: 11.08.06
JC			PAGE: 1 OF 1
			SCALE: N/A